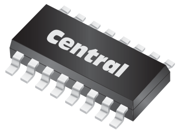
Material Composition Specification

SOIC-16 Case



Device average mass . . . . **145 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.66%	3.86	Si	7440-21-3	2.66%	3.86	26,621
bond wire	gold	0.28%	0.4	Au	7440-57-5	0.28%	0.4	2,759
leadframe	copper	31.38%	45.5	Cu	7440-50-8	31.38%	45.5	313,793
die attach	silver epoxy	0.3%	0.44	Ag	7440-22-4	0.24%	0.35	2,414
				epoxy resin	Proprietary	0.06%	0.09	621
encapsulation	EMC	63.79%	92.5	silica (fused)	60676-86-0	44.9%	65.1	448,966
				epoxy resin	Proprietary	15.86%	23.0	158,621
				Sb_2O_3	1309-64-4	1.24%	1.8	12,414
				TBBA	79-94-7	1.52%	2.2	15,172
				carbon	1333-86-4	0.28%	0.4	2,759
plating*	tin/lead process	1.59%	2.3	Sn	7440-31-5	1.34%	1.95	13,448
				Pb	7439-92-1	0.24%	0.35	2,414
	matte tin	1.59%	2.3	Sn	7440-31-5	1.59%	2.3	15,862

*For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

R3 (16-July 2018)